



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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D-Sub straight SMT connector



General information

Design	complementary to CECC 75301-802
No. of contacts	9,15,25,37
Contact spacing	Pitch is 2,76mm
Test voltage	1KV between contacts; 1,2 KV between shell and contact
Contact resistance	max. 25m0hm for contact; max.5m0hm for grounding
Insulation resistance	min. 5GΩ
Working current	5A max. at 20°C
Temperature range	-55°C ... +125°C
Termination technology	SMT
Clearance	min. 1,0mm between adjacent contacts; min.1,2mm between contacts and shell
Creepage	min. 1,0mm between adjacent contacts; min.1,2mm between contacts and shell
Insertion force	30N max. for 9P; 50N max. for 15P; 83N max. for 25P; 123N max. for 37P
Withdrawal force	3,3N min. for 9P; 4,5N min. for 15P; 7,8N min. for 25P; 11N min. for 37P
Mating cycles	250 Cycles for PL2; 500 cycles for PL1
UL file	E102079
RoHS - compliant	Yes
Hot plugging	No

Insulator material

Material	LCP (Liquid Crystalline Polymer)
Color	Black
UL classification	UL 94-V0
Material group acc. IEC 60664-1	IIIa (175 ≤ CTI < 400)

Grounding

Material	Copper alloy
Plating	Sn over Ni

Contact material

Contact material	Copper alloy
Plating termination zone	Sn over Ni
Plating contact zone	Au over PdNi

Current carrying capacity

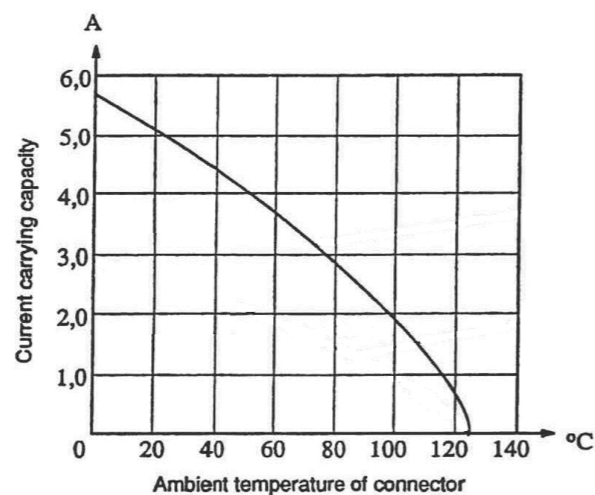
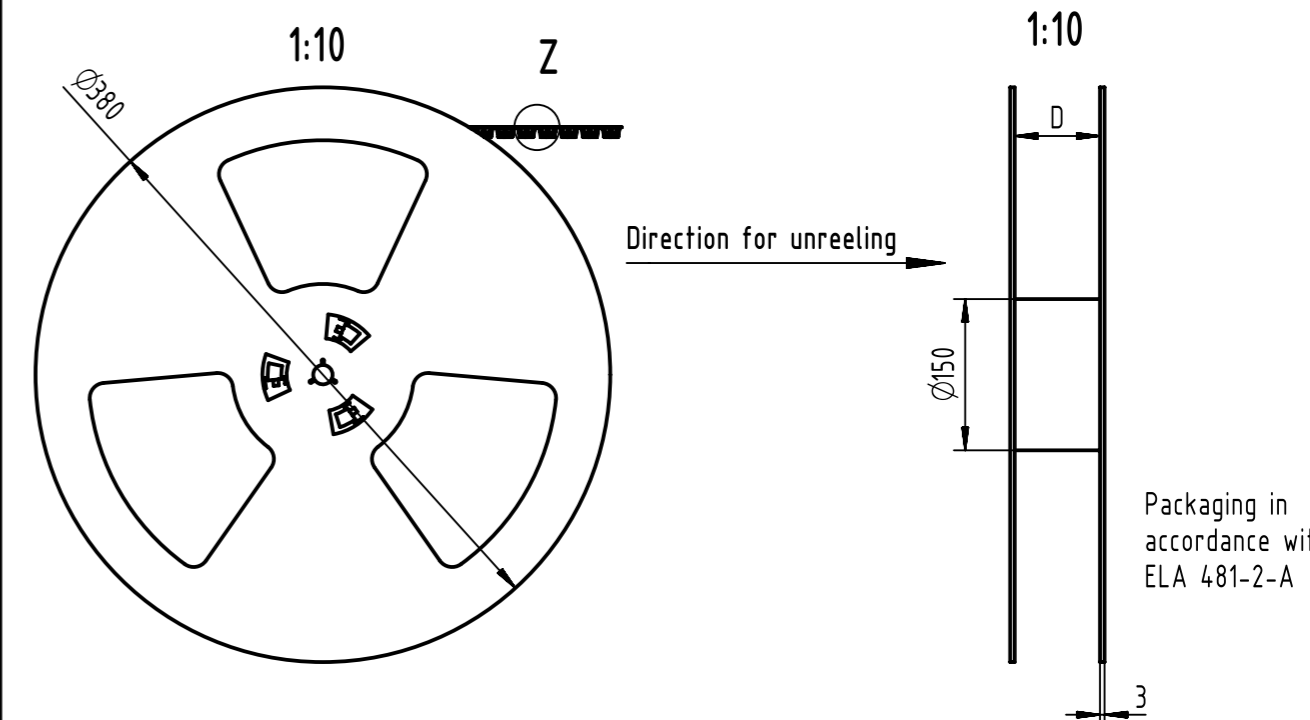
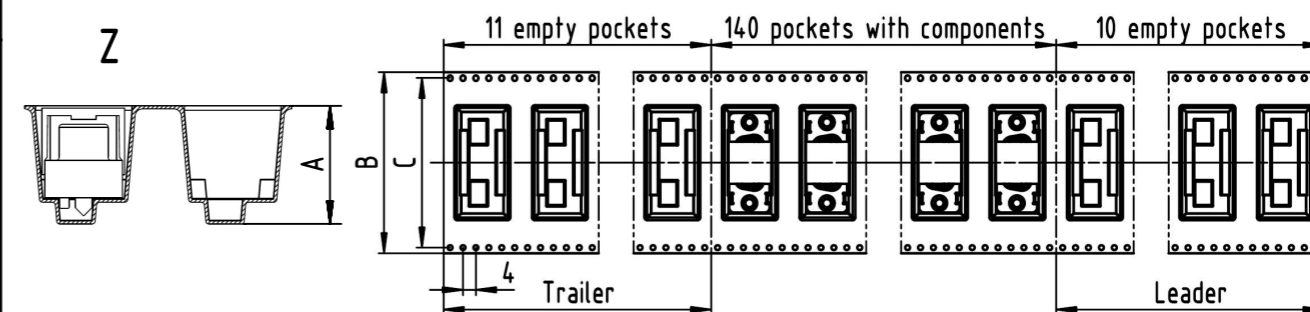


Figure is for 25-pole connector

Packing information



Packaging in accordance with ELA 481-2-A

Part number	A	B	C	D	Part number	A	B	C	D
0955 115 X6YZ 741	19,0	56,0	52,4	56,4	0955 155 X6YZ 741	19,0	56,0	52,4	56,4
0955 215 X6YZ 741	19,0	56,0	52,4	56,4	0955 255 X6YZ 741	19,0	56,0	52,4	56,4
0955 315 X6YZ 741	19,0	72,0	68,4	72,4	0955 355 X6YZ 741	19,0	72,0	68,4	72,4
0955 415 X6YZ 741	19,0	88,0	84,4	88,4	0955 455 X6YZ 741	19,0	88,0	84,4	88,4
0955 129 X8YZ 741	19,0	56,0	52,4	56,4	0955 169 X8YZ 741	19,0	56,0	52,4	56,4
0955 229 X8YZ 741	19,0	56,0	52,4	56,4	0955 269 X8YZ 741	19,0	56,0	52,4	56,4
0955 329 X8YZ 741	19,0	72,0	68,4	72,4	0955 369 X8YZ 741	19,0	72,0	68,4	72,4
0955 429 X8YZ 741	19,0	88,0	84,4	88,4	0955 469 X8YZ 741	19,0	88,0	84,4	88,4

X=3,6,7; Y=1,2; Z=1,2

X=3,6,7; Y=1,2; Z=1,2

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